



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-06-28
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	RVWV*UT93AA6	A	ZS1A	2017-06-28
Amount	UoM	Unit type	ST ECOPACK Grade	
16.00	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
tin is used or other bulk terminat	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
DSO	2.8x1.5x0.9	5	gull wing
Comment	Package: WV SOT 23 5L; MDF valid for LDS3985M25R		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RVWV*UT93AA6						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	0.881	mg	supplier	die	Silicon (Si)	7440-21-3		0.833	mg	945516	52063	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	7946	438	
				supplier	metallization	Tungsten (W)	7440-33-7		0.012	mg	13621	750	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	2270	125	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.017	mg	19296	1063	
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.001	mg	1135	63	
				supplier	polymer die coating	PIXI Gamma-butylolactone	96-48-0		0.009	mg	10216	563	
Leadframe	Copper & its alloys	6.920	mg	supplier	alloy	Copper (Cu)	7440-50-8		6.668	mg	963584	416750	
				supplier	alloy	Iron (Fe)	7439-89-6		0.154	mg	22254	9625	
				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	289	125	
				supplier	alloy	Zinc (Zn)	7440-66-6		0.009	mg	1301	563	
	Nickel (Ni)	supplier	metallization	Nickel (Ni)	7440-02-0		0.079	mg	11416	4938			
		supplier	metallization	Palladium (Pd)	7440-05-3		0.007	mg	1012	438			
	Precious metals	supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	145	63			
		Die attach	Other Organic Materials	0.064	mg	supplier	glue	Silver (Ag)	7440-22-4	0.044	mg	687500	2750
					supplier	glue	methylene diacrylate	42594-17-2		0.016	mg	250000	1000
					supplier	glue	Dicyclopentenylmethyl methacrylate	68586-19-6		0.002	mg	31250	125
supplier					glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.002	mg	31250	125	
supplier					wire	Copper (Cu)	7440-50-8		0.141	mg	1000000	8813	
Encapsulation	Other Organic Materials	7.994	mg	supplier	molding compound	Silica, vitreous	60676-86-0		7.177	mg	897798	448563	
				supplier	molding compound	phenolic resin	29690-82-2		0.295	mg	36903	18438	
				supplier	molding compound	epoxy resin	25068-38-6		0.337	mg	42157	21063	
				supplier	molding compound	Biphenyl epoxy resin	85954-11-6		0.168	mg	21016	10500	
				supplier	molding compound	carbon black	1333-86-4		0.017	mg	2127	1063	